

CPC**COOPERATIVE PATENT CLASSIFICATION****H01F****MAGNETS; INDUCTANCES; TRANSFORMERS; SELECTION OF MATERIALS FOR THEIR MAGNETIC PROPERTIES**

(ceramics based on ferrites [C04B 35/26](#); alloys [C22C](#); {construction of loading coils [H01B](#)} ; thermomagnetic devices [H01L 37/00](#); loudspeakers, microphones, gramophone pick-ups or like acoustic electromechanical transducers [H04R](#))

NOTE

In this subclass, inductances and transformers are regarded as being "for power supply" if they are intended for this purpose even in systems operating at frequencies above 60 cycles/sec.

H01F 1/00

Magnets or magnetic bodies characterised by the magnetic materials therefor; Selection of materials for their magnetic properties

H01F 1/0009

- {Antiferromagnetic materials, i.e. materials exhibiting a Néel transition temperature ([H01F 1/0036](#) takes precedence)}

WARNING

This groups is not complete pending the completion of reclassification; see provisionally also [H01F 1/00](#) - [H01F 1/447](#)

H01F 1/0018

- {Diamagnetic or paramagnetic materials, i.e. materials with low susceptibility and no hysteresis ([H01F 1/0036](#) takes precedence)}

H01F 1/0027

- {Thick magnetic films (forming thick magnetic films [H01F 41/16](#); magnetic record carriers [G11B 5/70](#))}

NOTE

Group [H01F 1/0036](#) takes precedence over groups [H01F 1/09](#), [H01F 1/11](#), [H01F 1/20](#), [H01F 1/33](#) and [H01F 1/36](#)

H01F 1/0036

- {showing low dimensional magnetism, i.e. spin rearrangements due to a restriction of dimensions, e.g. showing giant magnetoresistivity, ([H01F 1/153](#), [H01F 1/42](#) and [H01F 10/00](#) take precedence; magnetoresistive sensors [G01D 5/16](#), [G01R 33/06](#); magnetoresistive recording [G11B 5/39](#); magnetic-field-controlled resistors [H01L 43/08](#))}

H01F 1/0045

- • {Zero dimensional, e.g. nanoparticles, soft nanoparticles for medical/biological use (preparation of fullerenes in general [C01B 31/0206](#))}

H01F 1/0054

- • • {Coated nanoparticles, e.g. nanoparticles coated with organic surfactant}

H01F 1/0063

- • • {in a non-magnetic matrix, e.g. granular solids (granular films [H01F 10/007](#))}

H01F 1/0072

- • {one dimensional, i.e. linear or dendritic nanostructures}

H01F 1/0081

- • • {in a non-magnetic matrix, e.g. Fe-nanowires in a nanoporous membrane}

H01F 1/009

- • {bidimensional, e.g. nanoscale period nanomagnet arrays ([H01F 10/007](#) takes precedence)}

H01F 1/01

- of inorganic materials ([H01F 1/44](#) takes precedence)

- H01F 1/012 . . {adapted for magnetic entropy change by magnetocaloric effect, e.g. used as magnetic refrigerating material (refrigeration systems using magnetic effects [F25B 21/00](#))}
- H01F 1/015 . . . {Metals or alloys}
- H01F 1/017 . . . {Compounds}
- H01F 1/03 . . characterised by their coercivity {(H01F 1/40 takes precedence)}
- H01F 1/0302 . . . {characterised by unspecified or heterogeneous hardness or specially adapted for magnetic hardness transitions}
- H01F 1/0304 {adapted for large Barkhausen jumps or domain wall rotations, e.g. WIEGAND or MATTEUCCI effect (H01F 1/143 and H01F 1/15391 take precedence)}
- H01F 1/0306 {Metals or alloys, e.g. LAVES phase alloys of the $MgCu_2$ -type (H01F 1/0304 takes precedence)}
- H01F 1/0308 {with magnetic shape memory [MSM], i.e. with lattice transformations driven by a magnetic field, e.g. Heusler alloys}
- H01F 1/0311 {Compounds (H01F 1/0304 takes precedence)}
- H01F 1/0313 {Oxidic compounds}
- H01F 1/0315 {Ferrites}
- H01F 1/0317 {Manganites}
- H01F 1/032 . . . of hard-magnetic materials
- H01F 1/04 Metals or alloys
- H01F 1/047 Alloys characterised by their composition

NOTE

In groups [H01F 1/053](#) to [H01F 1/059](#), an alloy is classified in the last appropriate place

- H01F 1/053 containing rare earth metals
- H01F 1/0533 {in a bonding agent}
- H01F 1/0536 {sintered}
- H01F 1/055 and magnetic transition metals, e.g. $SmCo_5$
- H01F 1/0551 {in the form of particles, e.g. rapid quenched powders or ribbon flakes}
- H01F 1/0552 {with a protective layer}
- H01F 1/0553 {obtained by reduction or by hydrogen decrepitation or embrittlement}
- H01F 1/0555 {pressed, sintered or bonded together}
- H01F 1/0556 {pressed}
- H01F 1/0557 {sintered}
- H01F 1/0558 {bonded together}
- H01F 1/057 and IIIa elements, e.g. $Nd_2Fe_{14}B$
- H01F 1/0571 {in the form of particles, e.g. rapid quenched powders or ribbon flakes}
- H01F 1/0572 {with a protective layer}

H01F 1/0573	{obtained by reduction or by hydrogen decrepitation or embrittlement}
H01F 1/0574	{obtained by liquid dynamic compaction}
H01F 1/0575	{pressed, sintered or bonded together}
H01F 1/0576	{pressed, e.g. hot working}
H01F 1/0577	{sintered}
H01F 1/0578	{bonded together}
H01F 1/0579	{with exchange spin coupling between hard and soft nanophases, e.g. nanocomposite spring magnets}
H01F 1/058	and IVa elements, e.g. $\text{Gd}_2\text{Fe}_{14}\text{C}$
H01F 1/059	and Va elements, e.g. $\text{Sm}_2\text{Fe}_{17}\text{N}_2$
H01F 1/0593	{of tetragonal ThMn_{12} -structure}
H01F 1/0596	{of rhombic or rhombohedral $\text{Th}_2\text{Zn}_{17}$ structure or hexagonal $\text{Th}_2\text{Ni}_{17}$ structure}
H01F 1/06	in the form of particles, e.g. powder (H01F 1/047 takes precedence; {record carriers G11B 5/70605 })
H01F 1/061	{with a protective layer}
H01F 1/063	{with a non magnetic core}
H01F 1/065	{obtained by a reduction}
H01F 1/066	{obtained by liquid dynamic compaction}
H01F 1/068	{having a L10 crystallographic structure, e.g. $[\text{Co},\text{Fe}][\text{Pt},\text{Pd}]$ (nano)particles}

WARNING

This groups is not complete pending the completion of reclassification; see provisionally also [H01F 1/06](#) - [H01F 1/066](#)

H01F 1/08	pressed, sintered, or bound together
H01F 1/083	{in a bonding agent}
H01F 1/086	{sintered}
H01F 1/09	Mixtures of metallic and non-metallic particles; Metallic particles having oxide skin
H01F 1/10	Non-metallic substances, e.g. ferrites {e.g. $[(\text{Ba},\text{Sr})\text{O}(\text{Fe}_2\text{O}_3)_6]$ ferrites with hexagonal structure}
H01F 1/11	in the form of particles {(for magnetic record carriers G11B 5/70626)}
H01F 1/111	{with a non-magnetic core}
H01F 1/112	{with a skin (H01F 1/113 takes precedence)}
H01F 1/113	in a bonding agent
H01F 1/117	Flexible bodies
H01F 1/12	of soft-magnetic materials
H01F 1/14	Metals or alloys
H01F 1/143	{in the form of wires (H01F 1/147 takes precedence)}

H01F 1/147	Alloys characterised by their composition {(treatment thereof for enhancing their electromagnetic properties C21D 8/12)}
NOTE		
In groups H01F 1/14708 to H01F 1/15391 , an alloy is classified in the last appropriate place		
H01F 1/14708	{Fe-Ni based alloys (pure Fe or Ni H01F 1/14 , H01F 1/16 or H01F 1/20)}
H01F 1/14716	{in the form of sheets}
H01F 1/14725	{with insulating coating}
H01F 1/14733	{in the form of particles}
H01F 1/14741	{pressed, sintered or bonded together}
H01F 1/1475	{the particles being insulated}
H01F 1/14758	{by macromolecular organic substances}
H01F 1/14766	{Fe-Si based alloys}
H01F 1/14775	{in the form of sheets}
H01F 1/14783	{with insulating coating}
H01F 1/14791	{Fe-Si-Al based alloys, e.g. Sendust}
H01F 1/153	Amorphous metallic alloys, e.g. glassy metals {(making ferrous amorphous alloys C22C 33/003)}
H01F 1/15308	{based on Fe/Ni (H01F 1/15325 takes precedence)}
H01F 1/15316	{based on Co (H01F 1/15325 takes precedence)}
H01F 1/15325	{containing rare earths}
H01F 1/15333	{containing nanocrystallites, e.g. obtained by annealing}
H01F 1/15341	{Preparation processes therefor}
H01F 1/1535	{by powder metallurgy, e.g. spark erosion}
H01F 1/15358	{Making agglomerates therefrom, e.g. by pressing}
H01F 1/15366	{using a binder}
H01F 1/15375	{using polymers}
H01F 1/15383	{Applying coatings thereon (H01F 1/15366 takes precedence)}
H01F 1/15391	{Elongated structures, e.g. wires}
H01F 1/16	in the form of sheets (H01F 1/147 takes precedence)
H01F 1/18	with insulating coating
H01F 1/20	in the form of particles, e.g. powder (H01F 1/147 takes precedence)
H01F 1/22	pressed, sintered, or bound together
H01F 1/24	the particles being insulated
H01F 1/26	by macromolecular organic substances
H01F 1/28	dispersed or suspended in a bonding agent
H01F 1/33	Mixtures of metallic and non-metallic particles; Metallic particles having oxide skin

- H01F 1/34 Non-metallic substances, e.g. ferrites
- H01F 1/342 {Oxides ([H01F 1/36](#) and [H01F 1/38](#) take precedence)}
- H01F 1/344 {Ferrites, e.g. having a cubic spinel structure (X₂+O)(Y₂₃+O₃); e.g. magnetite Fe₃O₄}
- H01F 1/346 {[(TO₄)₃] with T= Si, Al, Fe, Ga ([H01F 10/24](#) takes precedence; Faraday rotators [G02F 1/09](#))}
- H01F 1/348 {Hexaferrites with decreased hardness or anisotropy, i.e. with increased permeability in the microwave (GHz) range, e.g. having a hexagonal crystallographic structure}
- H01F 1/36 in the form of particles {([H01F 1/346](#), [H01F 1/348](#) and [H01F 1/38](#) take precedence)}
- H01F 1/37 in a bonding agent
- H01F 1/375 Flexible bodies
- H01F 1/38 amorphous, e.g. amorphous oxides
- H01F 1/40 . . of magnetic semiconductor materials, e.g. CdCr₂S₄ (devices using galvanomagnetic or similar effects [H01L 43/00](#))
- H01F 1/401 . . . {diluted}

NOTE

In group [H01F 1/401](#), a diluted magnetic semiconductor (DMS) is classified in the last appropriate place

- H01F 1/402 {of II-VI type, e.g. Zn_{1-x}Cr_xSe}
- H01F 1/404 {of III-V type, e.g. In_{1-x}Mn_xAs}
- H01F 1/405 {of IV type, e.g. Ge_{1-x}Mn_x}
- H01F 1/407 {Diluted non-magnetic ions in a magnetic cation-sublattice, e.g. perovskites, La_{1-x}(Ba,Sr)_xMnO₃}
- H01F 1/408 . . . {half-metallic, i.e. having only one electronic spin direction at the Fermi level, e.g. CrO₂, Heusler alloys ([H01F 10/1936](#) takes precedence)}
- H01F 1/42 . of organic or organo-metallic materials, {e.g. graphene} ([H01F 1/44](#) takes precedence)
- H01F 1/44 . of magnetic liquids, e.g. ferrofluids (particles in a bonding agent [H01F 1/28](#), [H01F 1/36](#), [H01F 1/37](#))
- H01F 1/442 . . {the magnetic component being a metal or alloy, e.g. Fe ([H01F 1/447](#) takes precedence)}
- H01F 1/445 . . {the magnetic component being a compound, e.g. Fe₃O₄ ([H01F 1/447](#) takes precedence)}
- H01F 1/447 . . {characterised by magnetoviscosity, e.g. magnetorheological, magnetorheotropic, magnetodilatant liquids (electrorheological fluids [C10M 171/001](#))}

H01F 3/00 **Cores, Yokes, or armatures** (magnetic materials [H01F 1/00](#); permanent magnets [H01F 7/02](#))

- H01F 2003/005 . {Magnetic cores for receiving several windings with perpendicular axes, e.g. for antennae or inductive power transfer}
- H01F 3/02 . made from sheets

H01F 3/04	• made from strips or ribbons
H01F 3/06	• made from wires
H01F 3/08	• made from powder (powder coatings on sheets H01F 3/02 ; on strips or ribbons H01F 3/04 ; on wires H01F 3/06)
H01F 3/10	• Composite arrangements of magnetic circuits
H01F 2003/103	• • {Magnetic circuits with permanent magnets}
H01F 2003/106	• • {Magnetic circuits using combinations of different magnetic materials}
H01F 3/12	• • Magnetic shunt paths
H01F 3/14	• • Constrictions; Gaps, e.g. air-gaps (in magnetic shunt paths H01F 3/12)
H01F 5/00	Coils (superconducting coils H01F 6/06 ; fixed inductances of the signal type H01F 17/00)
H01F 5/003	• {Printed circuit coils}
H01F 2005/006	• {with conical spiral form}
H01F 5/02	• wound on non-magnetic supports, e.g. formers
H01F 2005/022	• • {wound on formers with several winding chambers separated by flanges, e.g. for high voltage applications}
H01F 2005/025	• • {wound on coaxial arrangement of two or more formers}
H01F 2005/027	• • {wound on formers for receiving several coils with perpendicular winding axes, e.g. for antennae or inductive power transfer}
H01F 5/04	• Arrangements of electric connections to coils, e.g. leads
H01F 2005/043	• • {having multiple pin terminals, e.g. arranged in two parallel lines at both sides of the coil}
H01F 2005/046	• • {Details of formers and pin terminals related to mounting on printed circuits}
H01F 5/06	• Insulation of windings
H01F 6/00	Superconducting magnets; Superconducting coils {(magnetic resonance assemblies using superconducting coil systems G01R 33/3815)}
H01F 2006/001	• {Constructive details of inductive current limiters}
H01F 6/003	• {Methods and means for discharging superconductive storage (superconducting alloys C22C ; static memories with superconducting elements G11C 11/44 ; superconducting circuit breakers with contacts H01H 33/004 ; superconducting material H01L 39/00 ; power cryotons H01L 39/20 ; superconducting switches for low power H03K 17/92)}
H01F 6/005	• {Methods and means for increasing the stored energy in superconductive coils by increments (flux pumps)}
H01F 6/006	• {Supplying energising or de-energising current; Flux pumps}
H01F 6/008	• • {Electric circuit arrangements for energising superconductive electromagnets}
H01F 6/02	• Quenching; Protection arrangements during quenching {(protection circuits H02H 7/001)}
H01F 6/04	• Cooling
H01F 6/06	• Coils, e.g. winding, insulating, terminating or casing arrangements therefor
H01F 6/065	• • {Feed-through bushings, terminals and joints (leading of conductors or axles through casings of transformers H01F 27/04)}

H01F 7/00

Magnets (superconducting magnets [H01F 6/00](#); for separation of solid materials or fluids [B03C 1/00](#); for bench or like work-holders [B23B 31/28](#), [B23Q 3/00](#); work-holding devices [B25B 11/00](#); lifting magnets [B66C 1/00](#); {operating or controlling locks using permanent magnets [E05B 47/0038](#); devices for holding a wing, e.g. door or window, by magnetic or electromagnetic attraction [E05C 19/16](#); relieving load or bearings using magnetic means [F16C 39/06](#)} ; for electric meters [G01R](#); for relays [H01H](#); {for electric discharge tubes [H01J](#), e.g. [H01J 3/24](#), [H01J 23/10](#), [H01J 29/68](#)} ; for dynamo-electric machines [H02K](#))

- H01F 7/02
 - Permanent magnets {[PM]}
- H01F 7/0205
 - • {Magnetic circuits with PM in general}
- H01F 7/021
 - • • {Construction of PM ([H01F 7/0278](#) takes precedence; PM compositions [H01F 1/032](#))}
- H01F 7/0215
 - • • • {Flexible forms, sheets}
- H01F 7/0221
 - • • {Mounting means for PM, supporting, coating, encapsulating PM}
- H01F 7/0226
 - • • {PM with variable field strength ([H01F 7/0284](#) takes precedence)}
- H01F 7/0231
 - • {Magnetic circuits with PM for power or force generation}
- H01F 7/0236
 - • • {Magnetic suspension or levitation (for vehicles [B60L 13/04](#); magnetic bearings [F16C 39/063](#))}
- H01F 7/0242
 - • • {Magnetic drives, magnetic coupling devices}
- H01F 7/0247
 - • • {Orientating, locating, transporting arrangements}
- H01F 7/0252
 - • • {PM holding devices ([H01F 7/021](#), [H01F 7/0215](#), [H01F 7/0226](#) take precedence)}
- H01F 7/0257
 - • • • {Lifting, pick-up magnetic objects}
- H01F 7/0263
 - • • • {Closures, bags, bands, engagement devices with male and female parts}
- H01F 7/0268
 - • • • {Magnetic cylinders}
- H01F 7/0273
 - • {Magnetic circuits with PM for magnetic field generation}
- H01F 7/0278
 - • • {for generating uniform fields, focusing, deflecting electrically charged particles (for magnetic separation by Lorentz force [B03C 1/023](#); specially adapted for NMR applications [G01R 33/383](#))}
- H01F 7/0284
 - • • • {using a trimmable or adjustable magnetic circuit, e.g. for a symmetric dipole or quadrupole magnetic field}
- H01F 7/0289
 - • • {Transducers, loudspeakers, moving coil arrangements}
- H01F 7/0294
 - • • {Detection, inspection, magnetic treatment}
- H01F 7/04
 - • Means for releasing the attractive force
- H01F 7/06
 - Electromagnets; Actuators including electromagnets {(electric coils [H01F 5/00](#); devices for holding workpieces using electric force [B23Q 3/15](#); load-engaging elements for lifting articles electromagnetically [B66C 1/06](#); electromagnetic couplings [F16D 27/00](#); magnetic brakes [F16D 63/002](#); electromagnetically operated valves [F16K 11/24](#), [F16K 31/00](#); magnetically locked mine lamps [F21L 11/00](#); analysing materials by magnetic means [G01N 27/72](#), [G01N 27/80](#); electromagnets for winding mechanical clocks [G04C 1/02](#); electromagnetic relays [H01H 51/00](#); windings for salient poles of dynamo-electric machines [H02K 3/18](#); electromagnets for telegraphic communication [H04L](#); for arc lamps [H05B 31/28](#))}
- H01F 2007/062
 - • {Details of terminals or connectors for electromagnets}

- H01F 7/064 . . {Circuit arrangements for actuating electromagnets (circuit arrangements for obtaining special operating characteristics [H01F 7/18](#); driving circuits for electromagnets making use of a switching regulator [H01H 47/325](#))}
- H01F 7/066 . . {Electromagnets with movable winding}
- H01F 2007/068 . . {using printed circuit coils}
- H01F 7/08 . . with armatures
- H01F 7/081 . . . {Magnetic constructions}
- H01F 2007/083 {External yoke surrounding the coil bobbin, e.g. made of bent magnetic sheet}
- H01F 2007/085 {Yoke or polar piece between coil bobbin and armature having a gap, e.g. filled with nonmagnetic material}
- H01F 2007/086 {Structural details of the armature}
- H01F 7/088 . . . {provided with means for absorbing shocks}
- H01F 7/10 . . . specially adapted for alternating current
- H01F 7/11 reducing or eliminating the effects of eddy currents
- H01F 7/12 having anti-chattering arrangements
- H01F 7/1205 {having short-circuited conductors (electromagnetic relays provided with short-circuited conducting sleeves [H01H 47/00](#))}
- H01F 7/121 . . . Guiding or setting position of armatures, e.g. retaining armatures in their end position
- H01F 7/122 by permanent magnets {([H01F 7/1615](#), [H01F 7/1646](#) take precedence)}
- H01F 7/123 by ancillary coil
- H01F 7/124 by mechanical latch, e.g. detent
- H01F 7/126 . . . Supporting or mounting
- H01F 7/127 . . . Assembling
- H01F 7/128 . . . Encapsulating, encasing or sealing
- H01F 7/129 of armatures
- H01F 7/13 . . . characterised by pulling-force characteristics
- H01F 7/14 . . . Pivoting armatures ([H01F 7/17](#) takes precedence)
- H01F 7/145 {Rotary electromagnets with variable gap (with fixed gap or torque motors [H02K 26/00](#))}
- H01F 7/16 . . . Rectilinearly-movable armatures ([H01F 7/17](#) takes precedence)
- H01F 7/1607 {Armatures entering the winding}
- H01F 7/1615 {Armatures or stationary parts of magnetic circuit having permanent magnet}
- H01F 7/1623 {Armatures having T-form}
- H01F 2007/163 {with axial bearing}
- H01F 7/1638 {Armatures not entering the winding}
- H01F 7/1646 {Armatures or stationary parts of magnetic circuit having permanent magnet}
- H01F 7/1653 {Magnetic circuit having axially spaced pole-pieces}
- H01F 2007/1661 {Electromagnets or actuators with anti-stick disc}

H01F 2007/1669	{Armatures actuated by current pulse, e.g. bistable actuators}
H01F 2007/1676	{Means for avoiding or reducing eddy currents in the magnetic circuit, e.g. radial slots}
H01F 2007/1684	{Armature position measurement using coils}
H01F 2007/1692	{Electromagnets or actuators with two coils}
H01F 7/17	. . .	Pivoting and rectilinearly-movable armatures
H01F 7/18	. . .	Circuit arrangements for obtaining desired operating characteristics, e.g. for slow operation, for sequential energisation of windings, for high-speed energisation of windings
H01F 7/1805	{Circuit arrangements for holding the operation of electromagnets or for holding the armature in attracted position with reduced energising current (for holding relay armature in attracted position with reduced energising current H01H 47/04 ; quick energising of electro-dynamic machines H02P 9/08 ; for quickly de-energising of dynamo-electric generators H02P 9/123)}
H01F 7/1811	{demagnetising upon switching off, removing residual magnetism}
H01F 7/1816	{making use of an energy accumulator (for relays H01H 47/043)}
H01F 2007/1822	{using a capacitor to produce a boost voltage}
H01F 7/1827	{by changing number of serially-connected turns or windings (for relays H01H 47/06)}
H01F 7/1833	{by changing number of parallel-connected turns or windings (for relays H01H 47/08)}
H01F 7/1838	{by switching-in or -out impedance (for relays H01H 47/10)}
H01F 7/1844	{Monitoring or fail-safe circuits (for relays H01H 47/002)}
H01F 2007/185	{with armature position measurement}
H01F 2007/1855	{using a stored table to deduce one variable from another}
H01F 2007/1861	{using derivative of measured variable}
H01F 2007/1866	{with regulation loop}
H01F 7/1872	{Bistable or bidirectional current devices (relays H01H 47/226)}
H01F 7/1877	{controlling a plurality of loads}
H01F 7/1883	{by steepening leading and trailing edges of magnetisation pulse, e.g. printer drivers}
H01F 2007/1888	{using pulse width modulation}
H01F 2007/1894	{minimizing impact energy on closure of magnetic circuit}
H01F 7/20	. .	without armatures (cores H01F 3/00 ; coils H01F 5/00 ; {shaping metal by applying magnetic forces B21D 26/14 ; electromagnets specially adapted for NMR applications G01R 33/381)}
H01F 7/202	. . .	{Electromagnets for high magnetic field strength (for superconducting electromagnets H01F 6/00 ; for transformers or inductances without a magnetic core H01F 30/08)}
H01F 7/204	{Circuits for energising or de-energising}
H01F 7/206	. . .	{Electromagnets for lifting, handling or transporting of magnetic pieces or material (electromagnets for guidance of vehicles, workpieces B65G 21/2009 ; for magnetic suspension or levitation H02N 15/00)}
H01F 2007/208	{combined with permanent magnets}

H01F 10/00

Thin magnetic films, e.g. of one-domain structure (magnetic record carriers [G11B 5/00](#); thin-film magnetic stores [G11C](#))

H01F 10/002

- {Antiferromagnetic thin films, i.e. films exhibiting a Néel transition temperature ([H01F 10/3218](#) and [H01F 10/3268](#) take precedence)}

WARNING

This groups is not complete pending the completion of reclassification; see provisionally also [H01F 10/00](#) - [H01F 10/30](#)

H01F 10/005

- {organic or organo-metallic films, e.g. monomolecular films obtained by Langmuir-Blodgett technique, graphene}

H01F 10/007

- {ultrathin or granular films ([H01F 10/005](#) and [H01F 10/3227](#) take precedence; applying ultrathin or granular layers to substrates [H01F 41/301](#))}

H01F 10/06

- characterised by the coupling or physical contact with connecting or interacting conductors

H01F 10/08

- characterised by magnetic layers ({[H01F 10/32](#) takes precedence } ; applying thin magnetic films to substrates [H01F 41/14](#))

H01F 10/10

- . characterised by the composition

H01F 10/12

- . . being metal or alloys (intermetallic compounds [H01F 10/18](#))

H01F 10/123

- . . . {having a L10 crystallographic structure, e.g. [Co,Fe][Pt,Pd] thin films}

WARNING

This groups is not complete pending the completion of reclassification; see provisionally also [H01F 10/16](#)

H01F 10/126

- {containing rare earth metals ([H01F 10/133](#) takes precedence)}

H01F 10/13

- Amorphous metallic alloys, e.g. glassy metals ({[H01F 10/3204](#) takes precedence})

NOTE

In this group, amorphous metallic alloys are classified in the last appropriate place

H01F 10/131

- {containing iron or nickel}

H01F 10/132

- {containing cobalt}

H01F 10/133

- {containing rare earth metals}

H01F 10/135

- {containing transition metals}

H01F 10/136

- {containing iron}

H01F 10/137

- {containing cobalt}

H01F 10/138

- {containing nanocrystallites, e.g. obtained by annealing}

H01F 10/14

- containing iron or nickel ({[H01F 10/126](#)}, [H01F 10/13](#), [H01F 10/16](#) take precedence)

NOTE

In this group, alloys containing iron or nickel are classified in the last appropriate place

H01F 10/142

- {containing Si}

- H01F 10/145 {containing Al, e.g. SENDUST}
- H01F 10/147 {with lattice under strain, e.g. expanded by interstitial nitrogen
([H01F 10/26](#) to [H01F 10/30](#) take precedence)}
- H01F 10/16 containing cobalt (([H01F 10/126](#)) , [H01F 10/13](#) take precedence)
- H01F 10/18 being compounds
- H01F 10/187 Amorphous compounds {([H01F 10/3204](#) takes precedence)}
- H01F 10/193 Magnetic semiconductor compounds {(in general [H01F 1/40](#);
multilayers, e.g. superlattices [H01F 10/3213](#))}
- H01F 10/1933 {Perovskites}

WARNING

This groups is not complete pending the completion of reclassification; see provisionally also [H01F 10/193](#)

- H01F 10/1936 {Half-metallic, e.g. epitaxial CrO₂ or NiMnSb films}
- H01F 10/20 Ferrites
- H01F 10/205 {Hexagonal ferrites}
- H01F 10/22 Orthoferrites {e.g. RFeO₃ (R= rare earth element) with
orthorhombic structure}
- H01F 10/24 Garnets {(in general [H01F 1/346](#); multilayers, e.g. superlattices
[H01F 10/3209](#); applying magnetic garnet films to substrates by
sputtering [H01F 41/186](#))}
- H01F 10/245 {Modifications for enhancing interaction with electromagnetic
wave energy}
- H01F 10/26 . . . characterised by the substrate or intermediate layers {([H01F 10/06](#) and
[H01F 10/32](#) take precedence)}
- H01F 10/265 . . . {Magnetic multilayers non exchange-coupled ([H01F 10/32](#) takes
precedence)}

WARNING

This groups is not complete pending the completion of reclassification; see provisionally also [H01F 10/00](#) - [H01F 10/30](#)

- H01F 10/28 . . . characterised by the composition of the substrate
- H01F 10/30 . . . characterised by the composition of the intermediate layers {e.g. seed,
buffer, template, diffusion preventing, cap layers ([H01F 10/06](#) and
[H01F 10/32](#) take precedence)}
- H01F 10/32 . . . Spin-exchange-coupled multilayers, e.g. nanostructured superlattices {(applying
spin-exchange-coupled multilayers to substrates [H01F 41/302](#))}
- H01F 10/3204 . . . {Exchange coupling of amorphous multilayers}
- H01F 10/3209 . . . {Exchange coupling of garnet multilayers}
- H01F 10/3213 . . . {Exchange coupling of magnetic semiconductor multilayers, e.g. MnSe/ZnSe
superlattices (semiconductor materials for use in semiconductor devices
[H01L 29/12](#))}
- H01F 10/3218 . . . {Exchange coupling of magnetic films via an antiferromagnetic interface
([H01F 10/3268](#) takes precedence)}
- H01F 10/3222 . . . {Exchange coupled hard/soft multilayers, e.g. CoPt/Co or NiFe/CoSm
(nanocomposite spring magnets [H01F 1/0579](#))}

- H01F 10/3227 . . {Exchange coupling via one or more magnetisable ultrathin or granular films}
 - H01F 10/3231 . . . {via a non-magnetic spacer}
 - H01F 10/3236 {made of a noble metal, e.g.(Co/Pt) n multilayers having perpendicular anisotropy ([H01F 10/3286](#) takes precedence)}
 - H01F 10/324 . . {Exchange coupling of magnetic film pairs via a very thin non-magnetic spacer, e.g. by exchange with conduction electrons of the spacer}
 - H01F 10/3245 . . . {the spacer being superconductive}
 - H01F 10/325 . . . {the spacer being noble metal}
 - H01F 10/3254 . . . {the spacer being semiconducting or insulating, e.g. for spin tunnel junction [STJ]}
 - H01F 10/3259 {Spin-exchange-coupled multilayers comprising at least a nano-oxide layer [NOL], e.g. with a NOL spacer}
 - H01F 10/3263 . . . {the exchange coupling being symmetric, e.g. for dual spin valve, e.g. NiO/Co/Cu/Co/Cu/Co/NiO}
 - H01F 10/3268 . . . {the exchange coupling being asymmetric, e.g. by use of additional pinning, by using antiferromagnetic or ferromagnetic coupling interface, i.e. so-called spin-valve [SV] structure, e.g. NiFe/Cu/NiFe/FeMn}
 - H01F 10/3272 {by use of anti-parallel coupled [APC] ferromagnetic layers, e.g. artificial ferrimagnets [AFI], artificial [AAF] or synthetic [SAF] anti-ferromagnets}
 - H01F 10/3277 {by use of artificial ferrimagnets [AFI] only}
 - H01F 10/3281 {only by use of asymmetry of the magnetic film pair itself, i.e. so-called pseudospin valve [PSV] structure, e.g. NiFe/Cu/Co}
 - H01F 10/3286 . . . {Spin-exchange coupled multilayers having at least one layer with perpendicular magnetic anisotropy}
 - H01F 10/329 . . . {Spin-exchange coupled multilayers wherein the magnetisation of the free layer is switched by a spin-polarised current, e.g. spin torque effect}
 - H01F 10/3295 . . . {Spin-exchange coupled multilayers wherein the magnetic pinned or free layers are laminated without anti-parallel coupling within the pinned and free layers}
- H01F 13/00** **Apparatus or processes for magnetising or demagnetising** ({devices for holding workpieces using magnetic or electric force acting directly on the workpieces [B23Q 3/15](#) ; for degaussing ships [B63G 9/06](#); for clocks or watches [G04D 9/00](#); {recording or erasing of information on magnetic record carriers [G11B 5/00](#) } ; demagnetising arrangements for colour television [H04N 9/29](#))
- H01F 13/003 . {Methods and devices for magnetising permanent magnets (permanent magnets [H01F 7/02](#))}
 - H01F 13/006 . {Methods and devices for demagnetising of magnetic bodies, e.g. workpieces, sheet material (for erasing of information on magnetic record carriers [G11B 5/00](#))}
- H01F 17/00** **Fixed inductances of the signal type** (coils in general [H01F 5/00](#) {inductors without a potential-jump or surface barrier specially adapted for integrated circuits, details thereof and multistep manufacturing processes therefor [H01L 28/10](#)})
- H01F 17/0006 . {Printed inductances (printed coils for dynamo-electric machines [H02K 3/26](#); printed circuits [H05K](#))}
 - H01F 17/0013 . . {with stacked layers ([H01F 27/2804](#) takes precedence)}

H01F 2017/002	. . . {Details of via holes for interconnecting the layers}
H01F 2017/0026	. . . {Multilayer LC-filter}
H01F 17/0033	. . {with the coil helically wound around a magnetic core}
H01F 2017/004	. . {with the coil helically wound around an axis without a core}
H01F 2017/0046	. . {with a conductive path having a bridge}
H01F 2017/0053	. . {with means to reduce eddy currents}
H01F 2017/006	. . {flexible printed inductors}
H01F 2017/0066	. . {with a magnetic layer}
H01F 2017/0073	. . {with a special conductive pattern, e.g. flat spiral}
H01F 2017/008	. . {Electric or magnetic shielding of printed inductances}
H01F 2017/0086	. . {on semiconductor substrate (inductors for integrated circuits H01L 28/10)}
H01F 2017/0093	. {Common mode choke coil}
H01F 17/02	. without magnetic core
H01F 17/03	. . with ceramic former
H01F 17/04	. with magnetic core
H01F 17/041	. . {Means for preventing rotation or displacement of the core}
H01F 17/043	. . {with two, usually identical or nearly identical parts enclosing completely the coil (pot cores)}
H01F 17/045	. . {with core of cylindric geometry and coil wound along its longitudinal axis, i.e. rod or drum core}
H01F 2017/046	. . . {helical coil made of flat wire, e.g. with smaller extension of wire cross section in the direction of the longitudinal axis}
H01F 2017/048	. . {with encapsulating core, e.g. made of resin and magnetic powder}
H01F 17/06	. . with core substantially closed in itself, e.g. toroid
H01F 17/062	. . . {Toroidal core with turns of coil around it}
H01F 2017/065	. . . {Core mounted around conductor to absorb noise, e.g. EMI filter}
H01F 2017/067	. . . {Core with two or more holes to lead through conductor}
H01F 17/08	. . . Loading coils for telecommunication circuits
H01F 19/00	Fixed transformers or mutual inductances of the signal type (H01F 36/00 takes precedence)
H01F 19/02	. Audio-frequency transformers or mutual inductances, i.e. not suitable for handling frequencies considerably beyond the audio range
H01F 19/04	. Transformers or mutual inductances suitable for handling frequencies considerably beyond the audio range (resonant circuits H03H)
H01F 19/06	. . Broad-band transformers, e.g. suitable for handling frequencies well down into the audio range
H01F 19/08	. . Transformers having magnetic bias, e.g. for handling pulses
H01F 2019/085	. . . {Transformer for galvanic isolation}
H01F 21/00	Variable inductances or transformers of the signal type (H01F 36/00 takes precedence)
H01F 21/005	. {Inductances without magnetic core}

H01F 21/02	<ul style="list-style-type: none"> continuously variable, e.g. variometers
H01F 21/04	<ul style="list-style-type: none"> by relative movement of turns or parts of windings
H01F 21/06	<ul style="list-style-type: none"> by movement of core or part of core relative to the windings as a whole
H01F 21/065	<ul style="list-style-type: none"> {Measures for obtaining a desired relation between the position of the core and the inductance}
H01F 21/08	<ul style="list-style-type: none"> by varying the permeability of the core, e.g. by varying magnetic bias
H01F 21/10	<ul style="list-style-type: none"> by means of a movable shield
H01F 21/12	<ul style="list-style-type: none"> discontinuously variable, e.g. tapped
H01F 2021/125	<ul style="list-style-type: none"> {Printed variable inductor with taps, e.g. for VCO}
H01F 27/00	Details of transformers or inductances, in general
H01F 27/002	<ul style="list-style-type: none"> {Arrangements provided on the transformer facilitating its transport}
H01F 27/004	<ul style="list-style-type: none"> {Arrangements for interchanging inductances, transformers or coils thereof}
H01F 27/006	<ul style="list-style-type: none"> {with special arrangement or spacing of turns of the winding(s), e.g. to produce desired self-resonance}
H01F 27/008	<ul style="list-style-type: none"> {with temperature compensation}
H01F 27/02	<ul style="list-style-type: none"> Casings
H01F 27/022	<ul style="list-style-type: none"> {Encapsulation}
H01F 27/025	<ul style="list-style-type: none"> {Constructional details relating to cooling}
H01F 27/027	<ul style="list-style-type: none"> {specially adapted for combination of signal type inductors or transformers with electronic circuits, e.g. mounting on printed circuit boards}
H01F 27/04	<ul style="list-style-type: none"> Leading of conductors or axles through casings, e.g. for tap-changing arrangements
H01F 27/06	<ul style="list-style-type: none"> Mounting, supporting or suspending transformers, reactors or choke coils {not being of the signal type}
H01F 2027/065	<ul style="list-style-type: none"> {Mounting on printed circuit boards}
H01F 27/08	<ul style="list-style-type: none"> Cooling (heat-transfer elements F28F); Ventilating (structural details of casings H01F 27/02)
H01F 27/085	<ul style="list-style-type: none"> {Cooling by ambient air}
H01F 27/10	<ul style="list-style-type: none"> Liquid cooling
H01F 27/105	<ul style="list-style-type: none"> {Cooling by special liquid or by liquid of particular composition}
H01F 27/12	<ul style="list-style-type: none"> Oil cooling
H01F 27/125	<ul style="list-style-type: none"> {Cooling by synthetic insulating and incombustible liquid}
H01F 27/14	<ul style="list-style-type: none"> Expansion chambers; Oil conservators; Gas cushions; Arrangements for purifying, drying, or filling
H01F 27/16	<ul style="list-style-type: none"> Water cooling
H01F 27/18	<ul style="list-style-type: none"> by evaporating liquids
H01F 27/20	<ul style="list-style-type: none"> Cooling by special gases or non-ambient air
H01F 27/22	<ul style="list-style-type: none"> Cooling by heat conduction through solid or powdered fillings
H01F 27/23	<ul style="list-style-type: none"> Corrosion protection
H01F 27/24	<ul style="list-style-type: none"> Magnetic cores
H01F 27/245	<ul style="list-style-type: none"> made from sheets, e.g. grain-oriented (H01F 27/26 takes precedence)

- H01F 27/2455 . . . {using bent laminations}
- H01F 27/25 . . made from strips or ribbons (H01F 27/26 takes precedence)
- H01F 27/255 . . made from particles (H01F 27/26 takes precedence)
- H01F 27/26 . . Fastening parts of the core together; Fastening or mounting the core on casing or support (on coil H01F 27/30)
- H01F 27/263 . . . {Fastening parts of the core together}
- H01F 27/266 . . . {Fastening or mounting the core on casing or support (on coil H01F 27/30)}
- H01F 27/28 . Coils; Windings; Conductive connections
- H01F 27/2804 . . {Printed windings}
- H01F 2027/2809 . . . {on stacked layers}
- H01F 2027/2814 . . . {with only part of the coil or of the winding in the printed circuit board, e.g. the remaining coil or winding sections can be made of wires or sheets}
- H01F 2027/2819 . . . {Planar transformers with printed windings, e.g. surrounded by two cores and to be mounted on printed circuit}
- H01F 27/2823 . . {Wires (H01F 27/2866 takes precedence)}
- H01F 27/2828 . . . {Construction of conductive connections, of leads}
- H01F 2027/2833 . . . {using coaxial cable as wire}
- H01F 2027/2838 . . . {using transposed wires}
- H01F 2027/2842 . . . {Wire coils wound in conical zigzag to reduce voltage between winding turns}
- H01F 27/2847 . . {Sheets; Strips (H01F 27/2866 takes precedence)}
- H01F 27/2852 . . . {Construction of conductive connections, of leads}
- H01F 2027/2857 . . . {Coil formed from wound foil conductor}
- H01F 2027/2861 . . . {Coil formed by folding a blank}
- H01F 27/2866 . . {Combination of wires and sheets}
- H01F 27/2871 . . {Pancake coils}
- H01F 27/2876 . . {Cooling (cooling transformers and inductances in general H01F 27/08)}
- H01F 27/288 . . {Shielding}
- H01F 27/2885 . . . {with shields or electrodes (shields or electrodes for pancake coils H01F 27/2871; construction of electric or magnetic shields or screens H01F 27/36)}
- H01F 27/289 . . . {with auxiliary windings (for pancake coils H01F 27/2871)}
- H01F 27/2895 . . {Windings disposed upon ring cores}
- H01F 27/29 . . Terminals; Tapping arrangements {for signal inductances}
- H01F 27/292 . . . {Surface mounted devices}
- H01F 2027/295 {with flexible terminals}
- H01F 2027/297 {with pin-like terminal to be inserted in hole of printed path}
- H01F 27/30 . . Fastening or clamping coils, windings, or parts thereof together; Fastening or mounting coils or windings on core, casing, or other support
- H01F 27/303 . . . {Clamping coils, windings or parts thereof together}

- H01F 27/306 . . . {Fastening or mounting coils or windings on core, casing or other support}
- H01F 27/32 . . Insulating of coils, windings, or parts thereof
- H01F 27/321 . . . {using a fluid for insulating purposes only}
- H01F 27/322 . . . {the insulation forming channels for circulation of the fluid}
- H01F 27/323 . . . {Insulation between winding turns, between winding layers}
- H01F 27/324 . . . {Insulation between coil and core, between different winding sections, around the coil; Other insulation structures}
- H01F 27/325 {Coil bobbins (formers for coils in general [H01F 5/02](#))}
- H01F 27/326 {specifically adapted for discharge lamp ballasts}
- H01F 27/327 . . . {Encapsulating or impregnating (encapsulating coil and core [H01F 27/022](#))}
- H01F 2027/328 {Dry-type transformer with encapsulated foil winding, e.g. windings coaxially arranged on core legs with spacers for cooling and with three phases}
- H01F 2027/329 . . . {Insulation with semiconducting layer, e.g. to reduce corona effect}
- H01F 27/33 . Arrangements for noise damping
- H01F 27/34 . Special means for preventing or reducing unwanted electric or magnetic effects, e.g. no-load losses, reactive currents, harmonics, oscillations, leakage fields
- H01F 27/341 . . {Preventing or reducing no-load losses or reactive currents}
- H01F 27/343 . . {Preventing or reducing surge voltages; oscillations}
- H01F 27/345 . . . {using auxiliary conductors}
- H01F 27/346 . . {Preventing or reducing leakage fields (using magnetic shields [H01F 27/365](#); using auxiliary windings [H01F 27/38](#))}
- H01F 2027/348 . . {Preventing eddy currents}
- H01F 27/36 . . Electric or magnetic shields or screens (movable for varying inductance [H01F 21/10](#))
- H01F 27/362 . . . {Electric shields or screens}
- H01F 27/365 . . . {Magnetic shields or screens}
- H01F 27/367 {using non-magnetic screens}
- H01F 27/38 . . Auxiliary core members; Auxiliary coils or windings
- H01F 27/385 . . . {for reducing harmonics}
- H01F 27/40 . Structural association with built-in electric component, e.g. fuse
- H01F 27/402 . . {Association of measuring or protective means}
- H01F 2027/404 . . . {Protective devices specially adapted for fluid filled transformers}
- H01F 2027/406 . . . {Temperature sensor or protection}
- H01F 2027/408 . . {Association with diode or rectifier}
- H01F 27/42 . Circuits specially adapted for the purpose of modifying, or compensating for, electric characteristics of transformers, reactors, or choke coils (circuits for controlling transformers, reactors or choke coils, for the purpose of obtaining a desired output [H02P 13/00](#); impedance networks [H03H](#))
- H01F 27/422 . . {for instrument transformers}
- H01F 27/425 . . . {for voltage transformers}

H01F 27/427	. . . {for current transformers}
H01F 29/00	Variable transformers or inductances not covered by group H01F 21/00 {(tap change devices H01H 9/0005)}
H01F 29/02	. with tapplings on coil or winding; with provision for rearrangement or interconnection of windings
H01F 29/025	. . {Constructional details of transformers or reactors with tapping on coil or windings}
H01F 29/04	. . having provision for tap-changing without interrupting the load current
H01F 29/06	. with current collector gliding or rolling on or along winding
H01F 29/08	. with core, coil, winding, or shield movable to offset variation of voltage or phase shift, e.g. induction regulators
H01F 29/10	. . having movable part of magnetic circuit {(high leakage transformers H01F 38/08 ; dynamo-electric machines with movable part of magnetic circuit H02K 23/44 , H02K 23/48)}
H01F 29/12	. . having movable coil, winding, or part thereof; having movable shield
H01F 29/14	. with variable magnetic bias ({amplitude modulation by means of variable impedance element H03C 1/08 ; magnetic amplifiers H03F ; {circuits for automatic telephonic communication H04M 3/00 })
H01F 29/143	. . {with control winding for generating magnetic bias}
H01F 29/146	. . {Constructional details}
H01F 30/00	Fixed transformers not covered by group H01F 19/00
H01F 30/02	. Auto-transformers
H01F 30/04	. having two or more secondary windings, each supplying a separate load, e.g. for radio set power supplies
H01F 30/06	. characterised by the structure
H01F 30/08	. . without magnetic core
H01F 30/10	. . Single-phase transformers (H01F 30/16 takes precedence)
H01F 30/12	. . Two-phase, three-phase or polyphase transformers
H01F 30/14	. . . for changing the number of phases
H01F 30/16	. . Toroidal transformers
H01F 36/00	Transformers with superconductive windings or with windings operating at cryogenic temperature (superconducting magnets or superconducting coils H01F 6/00)
H01F 37/00	Fixed inductances not covered by group H01F 17/00
H01F 37/005	. {without magnetic core}
H01F 38/00	Adaptations of transformers or inductances for specific applications or functions
H01F 2038/003	. {High frequency transformer for microwave oven}
H01F 2038/006	. {matrix transformer consisting of several interconnected individual transformers working as a whole}
H01F 38/02	. for non-linear operation

H01F 38/023	<ul style="list-style-type: none"> • . {of inductances}
H01F 2038/026	<ul style="list-style-type: none"> • . . {non-linear inductive arrangements for converters, e.g. with additional windings}
H01F 38/04	<ul style="list-style-type: none"> • . for frequency changing
H01F 38/06	<ul style="list-style-type: none"> • . for changing the wave shape
H01F 38/08	<ul style="list-style-type: none"> • High-leakage transformers or inductances
H01F 38/085	<ul style="list-style-type: none"> • . {Welding transformers}
H01F 38/10	<ul style="list-style-type: none"> • . Ballasts, e.g. for discharge lamps
H01F 38/12	<ul style="list-style-type: none"> • Ignition, e.g. for IC engines
H01F 2038/122	<ul style="list-style-type: none"> • . {with rod-shaped core}
H01F 2038/125	<ul style="list-style-type: none"> • . {with oil insulation}
H01F 2038/127	<ul style="list-style-type: none"> • . {with magnetic circuit including permanent magnet}
H01F 38/14	<ul style="list-style-type: none"> • Inductive couplings {(for charging batteries from ac mains by converters H02J 7/025)}
H01F 2038/143	<ul style="list-style-type: none"> • . {for signals}
H01F 2038/146	<ul style="list-style-type: none"> • . {in combination with capacitive coupling}
H01F 38/16	<ul style="list-style-type: none"> • Cascade transformers, e.g. for use with extra high tension
H01F 38/18	<ul style="list-style-type: none"> • Rotary transformers
H01F 38/20	<ul style="list-style-type: none"> • Instruments transformers
H01F 38/22	<ul style="list-style-type: none"> • . for single phase ac
H01F 38/24	<ul style="list-style-type: none"> • . . Voltage transformers
H01F 38/26	<ul style="list-style-type: none"> • . . . Constructions
H01F 38/28	<ul style="list-style-type: none"> • . . . Current transformers
H01F 38/30	<ul style="list-style-type: none"> • Constructions
H01F 2038/305	<ul style="list-style-type: none"> • {with toroidal magnetic core}
H01F 38/32	<ul style="list-style-type: none"> • Circuit arrangements
H01F 38/34	<ul style="list-style-type: none"> • . . . Combined voltage and current transformers
H01F 38/36	<ul style="list-style-type: none"> • Constructions
H01F 38/38	<ul style="list-style-type: none"> • . for polyphase ac
H01F 38/40	<ul style="list-style-type: none"> • . for dc
H01F 38/42	<ul style="list-style-type: none"> • Flyback transformers
H01F 2038/423	<ul style="list-style-type: none"> • . {with adjusting potentiometers}
H01F 2038/426	<ul style="list-style-type: none"> • . {with gap in transformer core}
H01F 41/00	Apparatus or processes specially adapted for manufacturing or assembling the devices covered by this subclass
H01F 41/005	<ul style="list-style-type: none"> • {Impregnating or encapsulating (insulating of windings H01F 41/12)}
H01F 41/02	<ul style="list-style-type: none"> • for manufacturing cores, coils, or magnets (H01F 41/14 takes precedence; for dynamo-electric machines H02K 15/00)
H01F 41/0206	<ul style="list-style-type: none"> • . {Manufacturing of magnetic cores by mechanical means (magnetic cores per se H01F 27/24)}

H01F 41/0213	. . .	{Manufacturing of magnetic circuits made from strip(s) or ribbon(s) (magnetic cores made by winding a ribbon H01F 27/25)}
H01F 41/022	{by winding the strips or ribbons around a coil}
H01F 41/0226	{from amorphous ribbons}
H01F 41/0233	. . .	{Manufacturing of magnetic circuits made from sheets (magnetic cores made from sheets H01F 27/245 ; soft magnetic alloys in the form of sheets H01F 1/16)}
H01F 41/024	{Manufacturing of magnetic circuits made from deformed sheets (magnetic cores made from deformed sheets H01F 27/2455)}
H01F 41/0246	. . .	{Manufacturing of magnetic circuits by moulding or by pressing powder (magnetic cores made by moulding or by pressing powder H01F 27/255 ; soft magnetic particles H01F 1/20 , H01F 1/36)}
H01F 41/0253	. .	{for manufacturing permanent magnets}
H01F 41/026	. . .	{protecting methods against environmental influences, e.g. oxygen, by surface treatment (magnetic particles with skin H01F 1/061 , H01F 1/09 , H01F 1/24 , H01F 1/33 and G11B 5/706)}
H01F 41/0266	. . .	{Moulding; Pressing (H01F 41/0273 takes precedence; hard magnetic particles H01F 1/06 , H01F 1/11)}
H01F 41/0273	. . .	{Imparting anisotropy (methods and devices for magnetising permanent magnets H01F 13/003)}
H01F 41/028	{Radial anisotropy (for rotor or stator bodies H02K 15/02)}
H01F 41/0286	. . .	{Trimming}
H01F 41/0293	. . .	{diffusion of rare earth elements, e.g. Tb, Dy or Ho, into permanent magnets}
H01F 41/04	. .	for manufacturing coils {(coils for transformer or inductances H01F 27/28)}
H01F 41/041	. . .	{Printed circuit coils (apparatus or processes for manufacturing printed circuits in general H05K 3/00)}
H01F 41/042	{by thin film techniques}
H01F 41/043	{by thick film techniques}
H01F 41/045	{Trimming}
H01F 41/046	{structurally combined with ferromagnetic material}
H01F 41/047	{structurally combined with superconductive material}
H01F 41/048	. . .	{Superconductive coils}
H01F 41/06	. . .	Winding
H01F 41/0604	{Winding sheet material}
H01F 41/0608	{with insulation}
H01F 41/0612	{Winding wire material}
H01F 41/0616	{with insulation}
H01F 41/062	{the insulation being strip material}
H01F 41/0625	{Winding more than one wire}
H01F 41/0629	{Twisting}
H01F 41/0633	{Devices for guiding or positioning the winding material on the winding form}
H01F 41/0637	{forming pancake coils}

- H01F 41/0641 {positioning the winding material in a special configuration on the winding form (orthocyclic coils, open mesh coils)}
 - H01F 41/0645 {using revolving flyers}
 - H01F 41/065 {Winding coils of special form}
 - H01F 41/0654 {Winding on elongate winding forms}
 - H01F 41/0658 {Winding flat coils}
 - H01F 2041/0662 {Winding saddle or deflection coils}
 - H01F 41/0666 {Winding with terminal wrapping or soldering; Winding while forming taps or terminals}
 - H01F 41/067 {Winding machines having a plurality of work holders or winding forms}
 - H01F 41/0675 {Turrets, turntables}
 - H01F 41/0679 {Tensioning or braking devices}
 - H01F 41/0683 {Dispensing or feeding devices}
 - H01F 41/0687 {Winding mandrels, winding forms}
 - H01F 41/0691 {Winding with deformation of the winding material section}
 - H01F 41/0695 {Winding while measuring electrical characteristics}
 - H01F 41/08 Winding conductors onto or threading conductors through cores or formers which are closed in themselves, e.g. toroids (for interconnecting digital storage elements [G11C 5/12](#))
 - H01F 41/10 Connecting leads to windings (making electric connections in general [H01R 43/00](#))
 - H01F 41/12 Insulating of windings ({impregnating or encapsulating of transformers [H01F 41/005](#)}; of conductors in general [H01B 13/06](#))
 - H01F 41/122 {Insulating between turns or between winding layers}
 - H01F 41/125 {Other insulating structures; Insulating between coil and core, between different winding sections, around the coil}
 - H01F 41/127 {Encapsulating or impregnating (encapsulating coil and core [H01F 41/005](#))}
 - H01F 41/14 for applying magnetic films to substrates (covering metals, or materials with metals, in general [C23C](#); manufacturing record carriers [G11B 5/84](#))
- NOTE**
- Group [H01F 41/30](#) takes precedence over groups [H01F 41/16](#) to [H01F 41/24](#), and over group [H01F 41/32](#)
- H01F 41/16 the magnetic material being applied in the form of particles, e.g. by serigraphy {i.e. forming thick magnetic films and precursors therefor, e.g. magnetisable pastes, inks, glass frits ([H01F 41/18](#) to [H01F 41/24](#) take precedence; thick magnetic films [H01F 1/0027](#))}
 - H01F 41/18 by cathode sputtering
 - H01F 41/183 {Sputtering targets therefor}
 - H01F 41/186 {for applying a magnetic garnet film (magnetic garnet materials [H01F 1/346](#); magnetic garnet films [H01F 10/24](#))}
 - H01F 41/20 by evaporation
 - H01F 41/205 {by laser ablation, e.g. pulsed laser deposition [PLD]}

- H01F 41/22 . . Heat treatment; Thermal decomposition; Chemical vapour deposition
 - H01F 41/24 . . from liquids
 - H01F 41/26 . . . using electric currents {e.g. electroplating}
 - H01F 41/28 . . . by liquid phase epitaxy
 - H01F 41/30 . . for applying nanostructures, e.g. by molecular beam epitaxy [MBE]
 - H01F 41/301 . . . {for applying ultrathin or granular layers (ultrathin or granular layers [H01F 10/007](#))}
 - H01F 41/302 . . . {for applying spin-exchange-coupled multilayers, e.g. nanostructured superlattices (spin-exchange-coupled multilayers [H01F 10/32](#))}
 - H01F 41/303 {with exchange coupling adjustment of magnetic film pairs, e.g. interface modifications by reduction, oxidation}
 - H01F 41/304 {using temporary decoupling, e.g. involving blocking, Néel or Curie temperature transitions by heat treatment in presence/absence of a magnetic field}
 - H01F 41/305 {applying the spacer or adjusting its interface, e.g. in order to enable particular effect different from exchange coupling}
 - H01F 41/306 {conductive spacer}
 - H01F 41/307 {insulating or semiconductive spacer}
 - H01F 41/308 {lift-off processes, e.g. ion milling, for trimming or patterning}
 - H01F 41/309 {electroless or electrodeposition processes from plating solution}
 - H01F 41/32 . . for applying conductive, insulating or magnetic material on a magnetic film {, specially adapted for a thin magnetic film}
 - H01F 41/325 . . {applying a noble metal capping on a spin-exchange-coupled multilayer e.g. spin filter deposition}
- WARNING**
- This groups is not complete pending the completion of reclassification;
see provisionally also [H01F 41/32](#)
- H01F 41/34 . . in patterns, e.g. by lithography